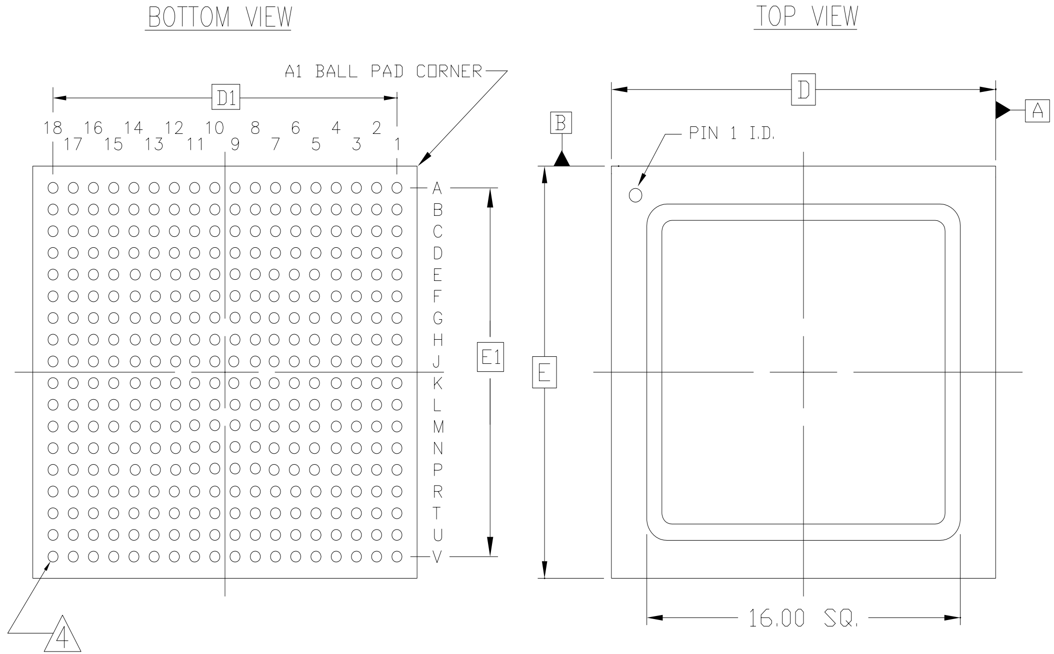
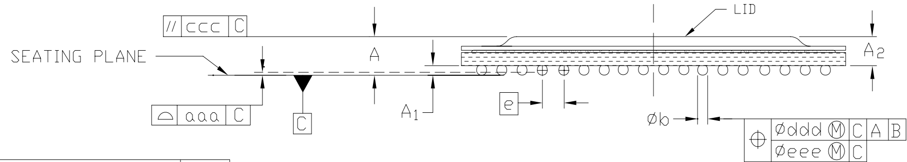
Flip-Chip BGA (FF323/FFG323) Package





SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.00	~	2.85	
A_1	0.40	~	0.60	
A_2	1.60	~	2.25	
D/E	19.00 BASIC			
D_1/E_1	17.00 REF			
e	1.00 BASIC			
ϕb	0.50	0.60	0.70	
aaa	~	~	0.20	
ccc	~	~	0.25	
ddd	~	~	0.25	
eee	~	~	0.10	
M	18			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAG-1
4. (triangle) SOLDER BALL COUNT = 324

323-BALL FLIP-CHIP BGA (FF323/FFG323)

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/07/07	1.0	Initial Xilinx release.
03/24/08	1.1	Updated JEDEC to MS-034-AAG-1